



In 2017, the International Conference on Trustworthy Systems and Their Applications (TSA) and the International Symposium on Dependable Computing and Internet of Things (DCIT) were merged into one large conference and renamed the International Conference on Dependable Systems and Their Applications (DSA). This year will be the tenth meeting after the merger. In the past, both TSA and DCIT were technically sponsored by the IEEE Reliability Society. Following the same tradition, DSA 2026 also has the same technical sponsorship from IEEE. The focus is on innovative methodologies, techniques, tools, and management to produce dependable and trustworthy systems and their applications more cost-effectively. In particular, this year's conference emphasizes using emerging AI and machine learning/deep learning technologies to further enhance existing approaches. DSA 2026 provides an opportunity for academic researchers, industry practitioners, and government policy and decision-makers to exchange ideas and results, share experiences, and explore possible solutions to overcome current challenges. It will be held from November 28-29 in Xiamen, China.

### TOPICS OF INTEREST

- ◆ Algorithms, Architecture, Framework, Design Patterns, and Maintenance for Dependable Systems and Software
- ◆ AI and ML/DL-based Techniques for System Dependability
- ◆ Dependability of Generative AI
- ◆ Security, Threats, Privacy, Safety, and Risk Management
- ◆ Dependability and Reliability Modeling and Measurement
- ◆ Requirements, Process, Standards, Productivity, and Project Management
- ◆ Quality Assurance, Maintenance, Reverse Engineering, and Re-Engineering
- ◆ Verification, Validation, and Testing
- ◆ Analysis, Debugging, Model Checking, and Program Repair
- ◆ Metrics, Measurement, and Quality Assessment
- ◆ Communication, Networking, Optimization, and Performance
- ◆ Fault Tolerance, Survivability, Resilience, and Availability
- ◆ Collaborative, Distributed, Embedded, Real-Time, High Performance, Highly Dependable, Intelligent, and Multimedia Systems
- ◆ Big Data and Analysis
- ◆ Prognostics and Health Management
- ◆ IoT, Supply Chain, Cyber-Physical Systems, Industry 4.0, and Smart City
- ◆ Empirical Studies, Benchmarking, and Industrial Best Practices
- ◆ Applications and Tools and Automation
- ◆ Approaching Artificial Creativity

### IMPORTANT DATES

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|--------------------|-------------------------------------|------------------------|-------------------------|
| ◆ October 10, 2026 | Regular & Short Papers due          | ◆ November 13, 2026    | Camera-ready due        |
| ◆ October 20, 2026 | Workshop Papers due                 | ◆ November 13, 2026    | Author registration due |
| ◆ October 20, 2026 | Fast Abstracts & Industry Track due | ◆ November 28-29, 2026 | Conference dates        |
| ◆ November 1, 2026 | Author notification                 |                        |                         |

### SUBMISSION

There are five types of submissions:

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|------------------|----------|------------------|----------|
| ◆ Regular Paper  | 12 pages | ◆ Fast Abstract  | 2 pages  |
| ◆ Short Paper    | 10 pages | ◆ Workshop Paper | 10 pages |
| ◆ Industry Paper | 2 pages  |                  |          |

Submit original manuscripts (not published or considered elsewhere). Each submission should include a title, the name and affiliation of each author, an abstract, and up to 6 keywords. The format must follow the [DSA proceedings format](#). At least one Best Paper Award will be presented. Detailed instructions for paper submission can be found at <https://dsa26.techconf.org/submission>.

### CONFERENCE PROCEEDINGS & SPECIAL ISSUES OF SCI JOURNALS

Conference proceedings will be published by the IEEE Conference Publishing Services (CPS). Papers in the proceedings will be submitted for inclusion in the IEEE Xplore and to all of the A&I (abstracting and indexing) partners (such as the Ei Compendex and Scopus). These papers will also appear in Google Scholar and the DBLP database.

### ORGANIZING COMMITTEE

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### GENERAL INQUIRIES

For more detailed and updated information, please refer to <https://dsa.techconf.org/>. For paper submission, review or other questions, please send emails to the [DSA Secretariat](#).